■DYNAMIC RAM MODULES

● 30 pin SIMM／SIP

Memory capacity [Bit]	Bit Configuration (Word×Bit)	Power supply voltage	Load memories	Package outline	Outward dimensions W×H×D (mm) In case of module with lead is loaded high	Contact Plating	Access time tRAC (ns)	Type No.
8M	1Mx8	5V±10%	M5M44400CJx2	One side	88.9×17.2×5.08	Ni+Solder plating SIMM	50	**MH1M08CAJ-5**
							60	**MH1M08CAJ-6**
							70	**MH1M08CAJ-7**
					78.9×19.0×5.08	Solder coat SIP	50	**MH1M08CAJA-5**
							60	**MH1M08CAJA-6**
							70	**MH1M08CAJA-7**
32M	4Mx8		M5M44100CJx8		88.9×20.3×5.08	Ni+Solder plating SIMM	50	**MH4M08CJ-5**
							60	**MH4M08CJ-6**
							70	**MH4M08CJ-7**
				One side	79.86×21×5.08	Solder coat SIP	50	**MH4M08CJA-5**
							60	**MH4M08CJA-6**
							70	**MH4M08CJA-7**
			M5M417400CJx2	One side	88.9×17.2×5.0	Ni+Solder plating SIMM	50	**MH4M08CAJ-5**
							60	**MH4M08CAJ-6**
							70	**MH4M08CAJ-7**
					78.9×18.0×5.0	Solder coat SIP	50	**MH4M08CAJA-5**
							60	**MH4M08CAJA-6**
							70	**MH4M08CAJA-7**
36M	4Mx9		M5M417400CJx2 +M5M44100CJx1	One side	88.9×17.2×5.0	Ni+Solder plating SIMM	50	**MH4M09CAJ-5**
							60	**MH4M09CAJ-6**
							70	**MH4M09CAJ-7**
					78.9×18.0×5.0	Solder coat SIP	50	**MH4M09CAJA-5**
							60	**MH4M09CAJA-6**
							70	**MH4M09CAJA-7**
128M	16Mx8		M5M416100BTPx8	Both sides	88.9×21.6×3.9	Ni+Solder plating SIMM	60	**MH16M08BTJ-6**
							70	**MH16M08BTJ-7**
144M	16Kx9		M5M416100BTPx9	Both sides	88.9×21.6×3.9	Ni+Solder plating SIMM	60	**MH16M09BTJ-6**
							70	**MH16M09BTJ-7**

● 72 pin SIMM

Memory capacity [Bit]	Bit Configuration (Word×Bit)	Power supply voltage	Load memories Bank Configuration	Package outline	Outward dimensions W×H×D (mm)	Contact Plating	Access time tRAC (ns)	Type No.
8M	256Kx32	5V±10%	M5M44260CJx2 2$\overline{\text{RAS}}$/1BANK	One side	107.95×17.5×5.0	Ni+Solder plating	60	**MH25632CNXJ-6**
							70	**MH25632CNXJ-7**
16M	512Kx32		M5M44260CJx4 4$\overline{\text{RAS}}$/1BANK	Both sides	107.95×20.2×8.6	Ni+Solder plating	60	**MH51232CNXJ-6**
							70	**MH51232CNXJ-7**
32M	1Mx32		M5M44400CJx8 2$\overline{\text{RAS}}$/1BANK	One side	107.95×25.4×5.08	Au plating	50	**MH1M32CDJ-5**
							60	**MH1M32CDJ-6**
							70	**MH1M32CDJ-7**
						Ni+Solder plating	50	**MH1M32CNDJ-5**
							60	**MH1M32CNDJ-6**
							70	**MH1M32CNDJ-7**
			M5M44405CJx8 2$\overline{\text{RAS}}$/1BANK	One side	107.95×25.4×5.08	Au plating	50	**MH1M325CDJ-5**
							60	**MH1M325CDJ-6**
							70	**MH1M325CDJ-7**
						Ni+Solder plating	50	**MH1M325CNDJ-5**
							60	**MH1M325CNDJ-6**
							70	**MH1M325CNDJ-7**
			M5M418160CJx2 2$\overline{\text{RAS}}$/1BANK	One side	107.95×20.2×5.0	Au plating	50	**MH1M32CXJ-5**
							60	**MH1M32CXJ-6**
							70	**MH1M32CXJ-7**
						Ni+Solder plating	50	**MH1M32CNXJ-5**
							60	**MH1M32CNXJ-6**
							70	**MH1M32CNXJ-7**
			M5M418165CJx2 2$\overline{\text{RAS}}$/1BANK EDO MODULE	One side	107.95×20.2×5.0	Au plating	50	**MH1M325CXJ-5**
							60	**MH1M325CXJ-6**
							70	**MH1M325CXJ-7**
						Ni+Solder plating	50	**MH1M325CNXJ-5**
							60	**MH1M325CNXJ-6**
							70	**MH1M325CNXJ-7**

★ : New product ★★ : Under development